CRMGGL1010B

N-Channel 100V, 8.8mΩ Typ. Power MOSFET

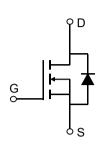
Description

Features

• 100V, 63A

$$R_{DS(ON)}$$
 Typ = 8.8m Ω @ V_{GS} = 10V
 $R_{DS(ON)}$ Typ = 11.8m Ω @ V_{GS} = 4.5V

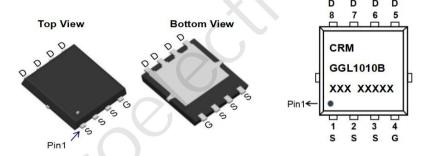
- Advanced Split Gate Trench Technology
- \bullet Excellent $R_{\text{DS}(\text{ON})}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGL1010B	CRMGGL1010B	PDFN5x6-8L	TAPING	13"	5000	50000

Absolute Maximum Ratings (@ $T_J = 25$ °C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		100	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	63	Α
I _D	Continuous Drain Current	T _C = 100°C	37.8	Α
I _{DM}	Pulsed Drain Current (1)		252	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		81	mJ
P_{D}	Power Dissipation	T _C = 25°C	78	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		1.6	°C/W
T_{J} , T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Char	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Char	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	1.8	2.4	V
В		$V_{GS} = 10V, I_D = 30A$	-	8.8	11.4	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 4.5V, I_D = 20A$	-	11.8	15.3	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-(1098	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V$, $V_{DS} = 50V$, f = 1MHz	X-\	413	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 11VII 12		5	-	pF
Q_g	Total Gate Charge		-	27	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 50V, I_{D} = 12A$	-	3.5	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} = 30 V, I _D = 12A	-	6.2	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime	.()	-	12.3	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	10	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_D = 12A, R_{GEN} = 3Ω	-	28	-	ns
t_f	Turn-Off Fall Time		-	13	-	ns
Drain-So	urce Diode Characteristics and I	Max Ratings				
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	63	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	252	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-	-	1.2	V

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =50V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =18A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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Test Circuit

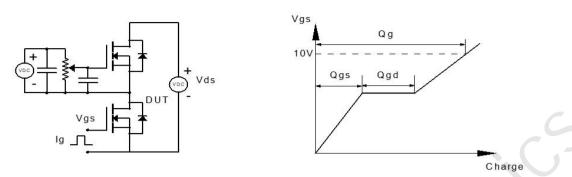


Figure 1: Gate Charge Test Circuit & Waveform

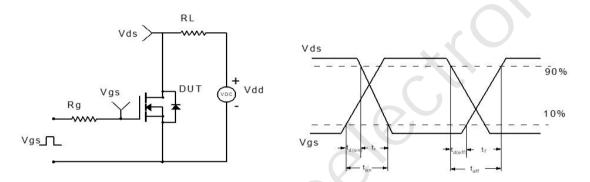


Figure 2: Resistive Switching Test Circuit & Waveform

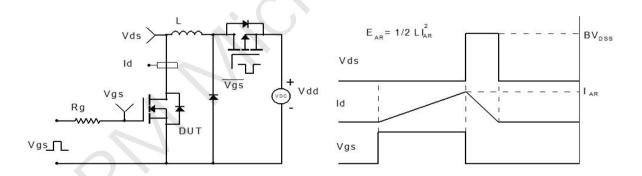


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

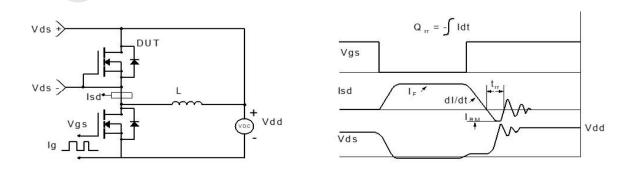
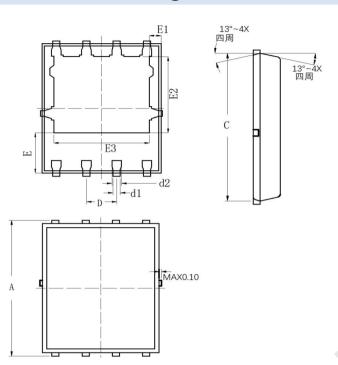


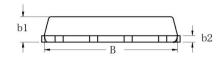
Figure 4: Diode Recovery Test Circuit & Waveform

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Package Mechanical Data(PDFN5x6-8L)





	COMMON DIM	MENSION (MM)	5		
PKG	PDFN 5×6-8L				
SYMBOL	MIN	TYP	MAX		
Α	6.000	6.100	6.200		
В	4.875	4.900	4.925		
b1	0.975	1.000	1.025		
b2	0.246	0.254	0.262		
С	5.775	5.800	5.825		
D	1.245	1.270	1.295		
d1	0.275	0.300	0.325		
d2	0.375	0.400	0.425		
E	1.725	1.775	1.825		
E1	0.395	0.445	0.495		
E2	3.425	3.475	3.525		
F3	3.960	4.010	4.060		

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